

ABSTRACT

The present invention provides a method of manufacturing a small electronic component, by which its yield can be enhanced. The invention comprises the steps of: a component mounting step of mounting a necessary electronic component 2-4 on a substrate 1; a coating layer forming step of forming a coating layer 14 for covering and sealing the substrate 1 in its entirety including the electronic component 2-4 with a coating material having high heat resistance; and a package layer forming step of forming a package layer 17 for covering and sealing a circumference of the coating layer 14 with a thermoplastic resin material 12. In the package layer forming step, adverse effects by the heat from the thermoplastic resin 12 to the electronic components 2-4 and the substrate 1 are inhibited with the coating layer 14.